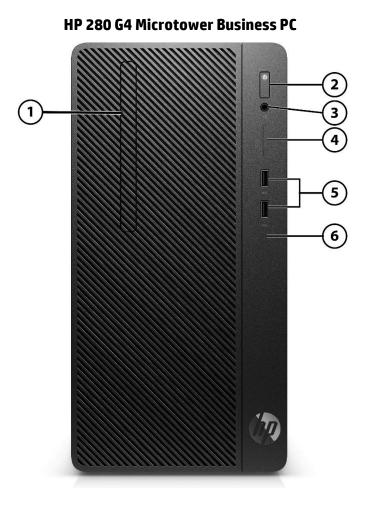
Overview



<u>Front</u>

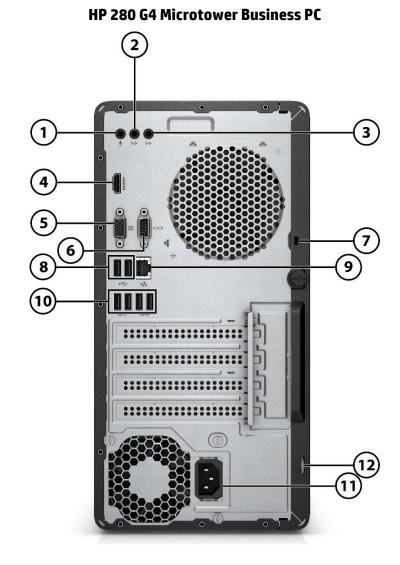
- 1. Slim-height Bay supporting an optical disk drive (optional)
- 2. Power Button
- 3. Combo jack, Headphone/ Microphone
- 4. SD Card Reader
- 5. (2) USB 3.1 Gen1 Port
- 6. HDD LED Light

<u>Not Shown</u>

- Slots (1) PCI Express x16
 - (1) PCI Express x1
 - (1) Legacy PCI (Optional)
 - (1) M.2 for WLAN
 - (1) M.2 2230/2280 storage
- Bays (1) 3.5" internal HDD bay
 - (1) 3.5" or 2.5" internal HDD bay (share bay)
 - (1) 9.5mm internal optical drive bay



Overview



<u>Back</u>

- 1. Audio Mic in
- 2. Audio Line out
- 3. Audio Link in
- 4. HDMI Port¹
- 5. VGA Port¹
- 6. Serial Port (optional, and available on legacy PCA only) Not Shown

(1) PS/2 Port (optional, and available on legacy PCA only)(2) Parallel Port (Optional via PCIex1 slot)

- 7. Security Lock Slot
- 8. (2) USB 2.0 port
- 9. RJ-45 Network Connector
- 10. (2) USB 3.1 Gen1 Port (left) and (2) USB 2.0 port (right)
- 11. Power Cord Connector
- 12. Padlock Loop

1. Port will be covered up when discrete graphic card is configured on shipped machine



Overview

AT A GLANCE

- Windows 10 Pro, Windows 10 Home or FreeDos 2.0
- Intel[®] H370 chipset supporting Intel[®] 8th generation Pentium[®], Core[™] i3 ,i5, i7 processors featuring Intel[®] UHD Graphics
- Supports an optional discrete graphics card
- Integrated 10/100/1000 Ethernet Controller or 802.11ac (1x1) WiFi and Bluetooth[®] 4.2 Combo
- Up to 32GB DDR4-2666 Unbuffered Memory (UDIMM)
- Independent monitor support via VGA and HDMI interfaces
- TPM 2.0 support (either dTPM or fTPM)¹
- Supports both Hard Disk Drives and SATA TLC / M.2 PCIe NVMe Solid State Drives
- Audio in, Audio out and Mic in support 5.1 channel
- 8 USB Ports (including 4 USB 3.1 Gen1 ports)
- 180W/310W 90% HE power supply
- Security cable lock supported (sold separately)
- Protected by HP Services; terms and conditions vary by country; certain restrictions and exclusions apply
- Dust filter available

TPM feature will not be supported on machine pre-configured with FreeDOS In cases, machines pre-configured with Windows OS might ship with TPM turned off

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Overview

PRODUCT NAME

HP 280 G4 Microtower Business PC

OPERATING SYSTEM

Preinstalled	Windows 10 Pro 64*
	Windows 10 Home 64*
Pre-installed (other)	FreeDOS 2.0

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/

PROCESSORS

Intel[®] Celeron^{®2,3}

CPU Intel Celeron G4900 Dual Core 3.1GHz 2400MHz 54W (Coffee Lake-S) (3.1 GHz, 2 MB cache, 2 cores) Intel® Pentium^{®2,3}

CPU Intel Pentium G5400 Dual Core 3.7GHz 2400MHz 54W (Coffee Lake-S) (3.7 GHz, 4 MB cache, 2 cores) Intel[®] Core™ i3^{2,3}

CPU Intel Core i3-8100 Quad Core 3.6GHz 2400MHz 65W (Coffee Lake-S) (3.6 GHz, 6 MB cache, 4 cores) Intel[®] Core™ i5^{2,3}

CPU Intel Core i5-8400 6C 2.8GHz 2666MHz 65W (Coffee Lake-S) (2.8GHz, turbo up to 4GHz, 9 MB cache, 6 cores) CPU Intel Core i5+ (Core i5 and Intel® Optane™ Memory⁴)

i5-8400 6C 2.8GHz 2666MHz 65W (Coffee Lake-S) (2.8GHz, turbo up to 4GHz, 9 MB cache, 6 cores) **Intel® Core™ i5**^{2,3}

CPU Intel Core i5-8500 6C 3.0GHz 2666MHz 65W (Coffee Lake-S) (3GHz, turbo up to 4.1GHz, 9 MB cache, 6 cores) CPU Intel Core i5 + (Core i5 and Intel[®] Optane[™] Memory⁴)

i5-8500 6C 3.0GHz 2666MHz 65W (Coffee Lake-S) (3GHz, turbo up to 4.1GHz, 9 MB cache, 6 cores) Intel[®] Core™ i7^{2,3}

CPU Intel Core i7-8700 6C 3.2GHz 2666MHz 65W (Coffee Lake-S) (3.2GHz, turbo up to 4.6GHz, 12 MB cache, 6 cores) CPU Intel Core i7 + (Core i7 and Intel[®] Optane[™] Memory⁴)

i7-8700 6C 3.2GHz 2666MHz 65W (Coffee Lake-S) (3.2GHz, turbo up to 4.6GHz, 12 MB cache, 6 cores)

2.Your product does not support Windows 8 or Windows 7, In accordance with Microsoft's support policy, HP does not support the Windows[®] 8 or Windows 7 operating system on products configured with Intel 8th generation and forward processors or provide any Windows[®] 8 or Windows 7 drivers on http://www.support.hp.com

3. Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. 64-bit computing system required. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering is not a measurement of higher performance. 4 Intel® Optane™ memory (cache) is sold separately. Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system. Available for HP commercial desktops and notebooks and for select HP workstations (HP Z240 Tower/SFF, Z2 Mini, ZBook Studio, 15 and 17 G5) and requires a SATA HDD, 7th Gen or higher Intel® Core™ processor or Intel® Xeon® processor E3-1200 V6 product family or higher, BIOS version with Intel® Optane™ supported, Windows 10 version 1703 or higher, M.2 type 2280-S1-B-M connector on a PCH Remapped PCIe Controller and Lanes in a x2 or x4 configuration with B-M keys that meet NVMe™ Spec 1.1, and an Intel® Rapid Storage Technology (Intel® RST) 15.5 driver.



Overview

CHIPSET

Intel[®] H370 Chipset

GRAPHICS

Integrated^{5,6}

Intel® UHD Graphics 630 (integrated on Core i7/i5/i3 processors) Intel® UHD Graphics 610 (integrated on Pentium G5400 and Celeron G4900)

Discrete Graphics

AMD Radeon™ R7 430 2GB PCIe x16 GFX NVIDIA® GeForce® GT730 1GB GFX NVIDIA® GeForce® GT730 2GB GFX NVIDIA® GeForce® GT1060 3GB GFX

5. HD content required to view HD images.

6. Integrated Intel software is available on select models only and requires separately purchased projector, tv or computer monitor with an integrated or external receiver. External receivers connect to the projector, tv or computer monitor via a standard VGA, HDMI cable, also sold separately

MEMORY⁷

Form Factor	Туре	Maximum	# of Slots
Microtower	DDR4 2666 (Transfer rates up to 2666 MT/s)	32 GB capacity	2 DIMM
4GB DDR4-2666 UDIMM NECC	4GB DDR4-2666 UDIMM NECC (1x4GB)		
8GB DDR4-2666 UDIMM NECC (1x8GB)			
8GB DDR4-2666 UDIMM NECC (2x4GB)			
16GB DDR4-2666 UDIMM NECC (1x16GB)			
16GB DDR4-2666 UDIMM NECC (2x8GB)			
7. Memory modules support data transfer rates up to 2666 MT/s; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate.			



Overview

STORAGE⁸

SATA3 - 3.5" or 2.5" 6Gb/s HDDs

2TB 7200 RPM SATA Hard Disk Drive 1TB 7200 RPM SATA Hard Disk Drive 500GB 7200 RPM SATA Hard Disk Drive 128GB 2.5" TLC SSD 256GB 2.5" TLC SSD

Solid State Drives 2.5"

128GB M.2 NVMe 256GB M.2 NVMe

SD Card Reader⁹ SD/SDHC/SDXC SD Card Reader

Intel Optane Memory¹⁰ SSD Intel 16GB 2280 Optance Memory

8. For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

9. Card sold separately

10. Optional per configuration

OPTICAL DISC DRIVES¹¹

DVD-ROM 9.5mm

DVD-Writer 9.5mm*

11. Optical drives are optional or add on features. Duplication of copyrighted material is strictly prohibited. Actual speeds may vary. Double Layer media compatibility will widely vary with some home DVD players and DVD-ROM drives.

NETWORKING¹²

Ethernet (RJ-45)

Integrated 10/100/1000M GbE LAN

Wi-Fi and Bluetooth®

802.11ac (1x1) WiFi and Bluetooth® 4.2 Combo

12. Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited.



Overview

AUDIO / MULTIMEDIA

Integrated Hi-Definition Audio Combo Jack, Headphone / Microphone Line-in / Line-out / Mic-in jacks (3.5mm)

KEYBOARDS AND POINTING DEVICES¹³

Keyboard

USB Business Slim Wired Keyboard HP USB Keyboard Business Slim USB Antimicrobial Wired Keyboard (China) Business Slim PS/2 Wired Keyboard No KB Option

Mouse

Antimicrobial USB Mouse (China) HP Optical USB Mouse Universal Wired Mouse USB USB Hardened Mouse (India) HP PS/2 Mouse (for machine configured with PS/2 port) No Mouse Option

13. Keyboards and mouse are optional or add-on features.

PORTS

Front

Slim-height Bay - supporting an optical disk drive (optional) Power Button Combo jack, Headphone / Microphone SD Card Reader (2) USB 3.1 Gen1 Port HDD LED Light

Not Shown

(1) PCI Express x16
 (1) PCI Express x1 (2.0) Accessory slot
 (1) Full-height PCI (Optional)
 (1) M.2 for WLAN
 (1) M.2 2230/2280 storage



Overview

Rear

Audio Mic in Audio Line out Audio Link in HDMI Port¹ VGA Port¹ Serial Port (optional, and available on legacy PCA only) Security Lock Slot (2) USB 2.0 port RJ-45 Network Connector (2) USB 3.1 Gen1 Port and (2) USB 2.0 Port Power Cord Connector Padlock loop

Not Shown

- (2) PS/2 Port (optional, and available on legacy PCA only)
- (1) Parallel Port (Optional via PCIex1 slot)

1: Port will be covered up when discrete graphic card is configured on shipped machine

BAYS

- (1) 9.5mm external slimline ODD bay (optional)
- (1) 3.5" internal HDD bay
- (1) 3.5 or 2.5" internal HDD bay (share bay)

ENVIRONMENTAL AND INDUSTRY

Environmental Data	Eco-Label Certifications & declarations	the following approva these marks: • IT ECO declaration • US ENERGY STAR® • EPEAT® Gold registe	ived or is in the process als and may be labeled w red in the United States net for registration statu	vith one or more of .*
	System Configuration	-	d for the Energy Consur for the Desktop model i	-
	Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz



HP 280 G4 Microtower Business PC

QuickSpecs

Overview

	12.97	13.03	13.39
Normal Operation	10.64	10.72	10.46
Sleep	0.78	0.76	0.77
Off	0.42	0.41	0.42
	Note: Energy efficience	y data listed is for an EN	IERGY STAR®
	compliant product if o	offered within the model	family. HP computers
	marked with the ENER	RGY STAR® Logo are com	pliant with the
	applicable U.S. Enviro	nmental Protection Age	ncy (EPA) ENERGY
	-	-	-
	-		_
	-		y, and a Microsoft
-			100VAC, 60Hz
(Short idle)			45.66
(Long idle)			35.67
			2.63
Off	1.43	1.4	1.43
	-		
Declared Noise	Sound Powe	er So	ound Pressure
Emissions	(L _{WAd} , bels)	(1	_{-pAm} , decibels)
ISO 7779 and ISO			
-	3.6		26.5
Idle			
Fixed Disk – Random writes	3.6		26.5
Longevity and			
Upgrading	years. Upgradeable featur include:	res and/or components cont	ained in the product may
	Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.		
Batteries			e 2006/66/EC
	Mercury greater the1ppm	by weight	
	Battery size: CR2032 (coin Battery type: Lithium	cell)	
	(Long idle) Sleep Off Heat Dissipation* Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) Typically Configured – Idle Fixed Disk – Random writes Longevity and Upgrading	(Short idle)10.64Normal Operation (Long idle)10.64Sleep0.78Off0.42Note: Energy efficiency compliant product if or marked with the ENER applicable U.S. Enviro STAR® specifications if offer ENERGY STAR® or efficiency data listed it hard disk drive, a high Windows® operating stHeat Dissipation*115VAC, 60HzNormal Operation (Long idle)44.23Normal Operation (Long idle)36.28Sleep2.66Off1.43*NOTE: Heat dissipatio assuming the serviceDeclared Noise Emissions (in accordance with ISO 7779 and ISO 9296)Sound Powe (Lwad, bels)Typically Configured – Idle3.6Fixed Disk – Random writes3.6Longevity and Upgrading"This product can be upgra years. Upgradeable featu include:Spare parts are available t years after the end of proor Batteries used in the prod Mercury greater the1ppm Cadmium greater than 200 Battery size: CR2032 (coin	(Short idle) 10.64 10.72 Normal Operation (Long idle) 10.64 10.72 Sleep 0.78 0.76 Off 0.42 0.41 Note: Energy efficiency data listed is for an EN compliant product if offered within the model marked with the ENERGY STAR® Logo are com applicable U.S. Environmental Protection Age STAR® specifications for computers. If a mode offer ENERGY STAR® compliant configuration: efficiency data listed is for a typically configu hard disk drive, a high efficiency power supply Windows® operating system. Heat Dissipation* 11SVAC, GOHz 230VAC, 50Hz Normal Operation 44.23 44.43 (Short idle) 36.28 36.56 Normal Operation 36.28 36.56 (Long idle) 2.66 2.59 Off 1.43 1.4 *NOTE: Heat dissipation is calculated based o assuming the service level is attained for one Declared Noise Emissions (in accordance with ISO 7779 and ISO 3296) Sound Power (L _{WAd} , bels) (ithe Fixed Disk – Random writes Longevity and Upgrading "This product can be upgraded, possibly extending its to years. Upgradeable features and/or components cont include: Spare parts are available throughout the warranty per years after the end of production. Batteries used in the product do not contain: Mercury greater the 1ppm by

Overview

Packaging Materials External: PAPER/Corrugated Internal: PLASTIC/EPE (Expanded Polyethylene) PLASTIC/Polyethylene low density - LDPE The plastic packaging material contains at least 50% recycled content. The plastic packaging materials contains at least 50% recycled content. Material Usage This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surfact designed to be frequently handled or carried by the user	Additional Information Packaging Materials
PLASTIC/Polyethylene low density - LDPE The plastic packaging material contains at least 50% recycled content. The corrugated paper packaging materials contains at least 75% recycled content. Material Usage Material Usage This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surfact designed to be frequently handled or carried by the user	
The plastic packaging material contains at least 50% recycled content. The corrugated paper packaging materials contains at least 75% recycled content. Material Usage This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surfact designed to be frequently handled or carried by the user	
The corrugated paper packaging materials contains at least 75% recycled content. Material Usage This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surfact designed to be frequently handled or carried by the user • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs)	
Material Usage This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mickel – finishes must not be used on the external surfact designed to be frequently handled or carried by the user • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs)	
excess of regulatory limits (refer to the HP General Specification the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): Asbestos Certain Azo Colorants Certain Brominated Flame Retardants – may not be used flame retardants in plastics Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel – finishes must not be used on the external surfac designed to be frequently handled or carried by the user Ozone Depleting Substances Polybrominated Biphenyls (PBBs)	Material U.S. S.
 Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCB) 	
 Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) – except for wires and cables, had been voluntarily removed from most applications. Radioactive Substances 	



Overview

	 Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	 HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP, Inc. Corporate Environmental Information	For more information about HP's commitment to the environment: Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp- information/environment/ecolabels.html ISO 14001 certificates: http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

*EPEAT® registered where applicable. EPEAT registration varies by country. See www.epeat.net for registration status by country



Overview

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Security and Protection

McAfee^{*} LiveSafe^{™ 11}

Productivity

Buy Office (sold separately) Dropbox¹²

ODD Playback and TV Tuners

Power Media Player 14 for HP with DVD (ODD SKU only)¹³

Movies

Netflix¹⁴

App Stores and Content Purchasing

Amazon¹⁴

HP Utilities and Support

HP Documentation HP JumpStart HP Recovery ManagerPBR HP Audio Switch HP Support Assistant¹⁵

BTB

HP Setup Integrated OOBE

Hardware Enabling Drivers or software utility HP ePrint¹⁶

HP System Event Utility

***NOTE**: Available for LA region only.

11. Free 1-year subscription of McAfee LiveSafe service included. Internet access required and not included. Subscription required after expiration

12. New Dropbox users are eligible to get 25 GB of Dropbox space free for 12 months from date of registration. For complete details and terms of use, including cancellation policies, visit the Dropbox website at https://www.dropbox.com/help/space/hp-promotion. Internet service required and not included.

13. Actual speeds may vary. Don't copy copyright-protected materials

14. Internet access required and not included.

15. Easily switch between speaker and microphone sources with intuitive controls and a consistent app experience

16. For more information visit hp.com/go/hpsupportassistant [Link will vary outside of the U.S.] HP Support Assistant is available for Android and Windows based PCs..

17. HP ePrint Driver requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of eligible printers, supported documents and image types and other HP ePrint details, see www.hp.com/go/eprintcenter). Print times and connection speeds may vary.

POWER SUPPLY¹⁶

```
180 W
ENERGY® STAR® Libra2 EPA90 (Gold) Full range 115V/230V
310 W
SFF ENTL EPA90 (Gold) Full range 115V/230V
```



Overview

16. All power supplies are not available in every region.

DIMENSIONS AND WEIGHT

Dimensions

6.69 x 13.3 x 10.79 in (170 x 338 x 274 mm)

Weight

11.9 lbs / 5.4 kg

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign
 matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the
 enclosure, and the same operating guidelines listed above will still apply.

Temperature Range	Operating: 32° to 104° F (0° to 40° C) ¹⁷ Non-operating: -22° to 140° F(-30° to 60° C)
Relative Humidity	Operating: 10% to 90% (non-condensing at ambient) Non-operating: 0% to 95% (non-condensing at ambient)
Maximum Altitude (unpressurized)	Operating: 10,000 ft (3048 m) Non-operating: 30,000 ft (9144 m)

17. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.



Overview

SERVICE AND SUPPORT

On-site Warranty 1: Available three-year (3-3-3) or one-year (1-1-1) limited warranty (varies by country) delivers on-site, next business day 2 service for parts and labor and complimentary limited technical support.3 Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack.4 To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical support applies only to HP-configured and third-party HP qualified hardware and software.

NOTE 4: Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Technical Specifications - Graphics

DisplayPort™	Multimode capable; supports HDCP, DisplayPort™ Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 3 displays (including the integrated panel)
Memory	Additional memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.
Maximum Graphics Memory	Windows 10: >4 GB
Maximum Color Depth	32 bits/pixel
Graphics/Video API Support	8th Generation Intel® Core Processors With Intel® UHD Graphics 630 DirectX 12, OpenGL 4.4, OpenCL 2.0, Intel® Quick Sync Video 8th Generation Pentium® G5400 and Celeron® G4900, With Intel® UHD Graphics 610 DirectX 12, OpenGL 4.4, OpenCL 2.0, Intel® Quick Sync Video
	Supported Display Resolutions and Refresh Rates
	800x600 @ 60 Hz
Resolution/ Refresh Rates	1024x768 @ 60 Hz
	1152x864 @ 60 Hz
	1280x600 @ 60 Hz
	1280x720 @ 60 Hz
	1280x800 @ 60 Hz
	1280x960 @ 60 Hz
	1280x1024 @ 60 Hz
	1360x768 @ 60 Hz
	1366x768 @ 60 Hz
	1400x1050 @ 60 Hz
	1440x900 @ 60 Hz
	1600x900 @ 60 Hz
	1600x1200[1] @ 60 Hz
	1680x1050 @ 60 Hz
	1920x1080 @ 60 Hz m graphics memory can be less than the amounts listed above depending upon your computer's

Technical Specifications - Graphics

NVIDIA® GeForce® GTX 1060 3GB Graphics Card

Engine Clock	1506 MHz
Memory Clock	4004 MHz
Memory Size(width)	3GB(192-bit)
Memory Type	128M x 32 GDDR5 @6pcs
Max. Resolution(DVI)	2560x1600@60Hz
Max. Resolution(HDMI)	4096x2160@60Hz
Max. Resolution(DP)	5120x3200@60Hz
Multi Display Support	4 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	DVI-D+HDMI+DPx3
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<120W
PCB form-factor with bracket	ATX (Full height) PCB with ATX dual slot bracket

NVIDIA® GeForce® GT730 1GB Graphics Card

Engine Clock	902 MHz
Memory Clock	1250 MHz
Memory Size(width)	1GB(64-bit)
Memory Type	128M x 32 GDDR5 @2pcs
Max. Resolution(DVI)	2560x1600@60Hz
Max. Resolution(HDMI)	4096x2160@24Hz
Multi Display Support	2 displays
HDCP Compliance	yes
Rear I/O connectors(bracket)	DVI+HDMI
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<35W
PCB form-factor with bracket	LP PCB with FH/LP bracket

Technical Specifications - Graphics

NVIDIA® GeForce® GT 730 2GB Graphics Card

Engine Clock	902 MHz
Memory Clock	1250 MHz
Memory Size(width)	2GB(64-bit)
Memory Type	256M x 32 GDDR5 @2pcs
Max. Resolution(DVI)	2560x1600@60Hz
Max. Resolution(DP)	4096x2160@60Hz
Multi Display Support	2 displays
HDCP Compliance	yes
Rear I/O connectors(bracket)	DVI+DP
Cooling(active/passive)	Active fan-sink(Active cooling with dynamic speed)
Total power consumption(W)	<35W
PCB form-factor with bracket	LP PCB with FH/LP bracket

AMD Radeon™ R7 430 2GB Graphics Card

Engine Clock	780 MHz
Memory Clock	1100 MHz
Memory Size(width)	2GB(128-bit)
Memory Type	128M x 32 GDDR5 @4pcs
Max. Resolution(VGA)	2048x1536
Max. Resolution(DP)	4096x2160@60Hz
Multi Display Support	2 displays
HDCP Compliance	yes
Rear I/O connectors(bracket)	VGA+DP
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP PCB with FH/LP bracket



Technical Specifications – Storage

HP 2 TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity	2 TB
Rotational Speed	7,200 rpm
Interface	SATA 6Gb/s NCQ
Buffer Size	64 MB
Logical Blocks	3,907,029,168
Seek Time	Read: <8.5 ms Write: <9.5 ms
Height	1.028 in/26.11 mm
Width	4.0 in/101.6 mm
Operating Temperature	32° to 140° F (0° to 60° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1 TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity	1 TB
Rotational Speed	7,200 rpm
Interface	Serial ATA 3.0 (6.0 Gb/s)
Buffer Size	32 MB
Logical Blocks	1,953,525,168
Seek Time	Single Track: 2.0 ms Average: 11 ms Full-Stroke: 21 ms
Height	1 in/2.54 cm
Width	Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm
Operating Temperature	41° to 131° F (5° to 55° C)
NOTE: For hard drives and solid state drives, $GB = 1$ billion bytes. $TB = 1$ trillion bytes. Actual formatted capacity is less. Up to	

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.



Technical Specifications – Storage

500 GB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity Rotational Speed Interface	500 GB 7,200 rpm Serial ATA 3.0 (6.0 Gb/s)
Buffer Size	32 MB
Logical Blocks	1,953,525,168
Seek Time	Single Track: 2.0 ms Average: 11 ms Full-Stroke: 21 ms
Height	1 in/2.54 cm
Width	Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP 9.5mm Desktop G2 Slim DVD Writer Drive

Height	9.5 mm height	
Orientation	Either horizontal or vertical	
Interface type	SATA/ATAPI	
Disc recording capacity	Up to 8.5 GB DL or 4.7 GB s	tandard
Dimensions (W x H x D)	•	
2	5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel	
Weight (max)	0.31 lb (140 g)	
Read Speeds	DVD-R DL	Up to 6X
	DVD+R	Up to 8X
	DVD+RW	Up to 8X
	DVD+R DL	Up to 6X
	DVD-R	Up to 8X
	DVD-RW	Up to 6X
	CD-R	Up to 24X
	CD-RW	Up to 10X
	DVD-RW, DVD+RW	Up to 8X
	DVD-R DL, DVD+R DL	Up to 8X
	DVD+R, DVD-R	Up to 8X
	DVD-ROM DL, DVD-ROM	Up to 8X
	CD-ROM, CD-R	Up to 24X
	CD-RW	Up to 24X
Access time (typical reads, including settling)		s (typical), CD-ROM: 170 ms (typical) ms (typical), CD-ROM: 320 ms (typical) al)
Power	•	ower receptacle DC ± 5%-100 mV ripple p-p nA typical, 1600 mA maximum)
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F Relative Humidity 10% to 8 Maximum Wet Bulb Tempe	30%



Technical Specifications – Storage

HP 9.5mm Desktop G2 Slim DVD-ROM Drive

Height	9.5 mm height	
Orientation	Either horizontal or vertical	
Interface type	SATA/ATAPI	
Disc recording capacity	Up to 8.5 GB DL or 4.7 GB s	tandard
Dimensions (W x H x D)	5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel	
Weight (max)	0.31 lb (140 q)	
-		
Read Speeds	DVD-R DL	Up to 6X
	DVD+R DVD+RW	Up to 8X
	DVD+RW DVD+R DL	Up to 8X
	DVD+R DL DVD-R	Up to 6X
	DVD-RW	Up to 8X Up to 6X
	CD-R	Up to 24X
	CD-RW	Up to 10X
	DVD-RW, DVD+RW	Up to 8X
	DVD-R DL, DVD+R DL	Up to 8X
	DVD+R, DVD-R	Up to 8X
	DVD-ROM DL, DVD-ROM	Up to 8X
	CD-ROM, CD-R	Up to 24X
	CD-RW	Up to 24X
Access time (typical reads, including settling)		s (typical), CD-ROM: 170 ms (typical) ms (typical), CD-ROM: 320 ms (typical) al)
Power	•	ower receptacle DC ± 5%-100 mV ripple p-p nA typical, 1600 mA maximum)
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F Relative Humidity 10% to 8 Maximum Wet Bulb Tempe	30%



Technical Specifications – Storage

128 GB PCIE NVME M.2 2280 (Non-SED) Solid State Drive

Unformatted Capacity	128 GB
Architecture	3D TLC NAND Flash
Interface	PCIE Gen3 x4
Form Factor	M.2 2280
Dimensions (W x H x D)	22mm x 80mm x 2.23mm
Weight	< 10g
Bandwidth Performance	Sequential Read: Up to 770 MB/s Sequential Write: Up to 450 MB/s Random Read: Up to 35K IOPs Random Write: Up to 91K IOPs
Power	Total Power Consumption (TYP) 100mW (Active) 40mW (Idle)
Useful Drive Life	72TBW
Environmental (all conditions, non- condensing)	Operating Temperature: 0° to 70°C Relative Humidity: 5% to 95% Shock: 1,000 G/0.5 ms
NOTE: For hard drives and solid sta	te drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256 GB PCIE NVME M.2 2280 (Non-SED) Solid State Drive

Unformatted Capacity	256 GB
Architecture	3D TLC NAND Flash
Interface	PCIE Gen3 x4
Form Factor	M.2 2280
Dimensions (W x H x D)	22mm x 80mm x 2.23mm
Weight	< 10g
Bandwidth Performance	Sequential Read: Up to 1570 MB/s Sequential Write: Up to 540 MB/s Random Read: Up to 71K IOPs Random Write: Up to 112K IOPs
Power	Total Power Consumption (TYP) 100mW (Active) 40mW (Idle)
Useful Drive Life	144TBW
Environmental (all conditions, non- condensing)	Operating Temperature: 0° to 70°C Relative Humidity: 5% to 95% Shock: 1,000 G/0.5 ms
NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to	

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.



Technical Specifications - Storage

128GB 2.5in SATA Three Layer Cell SSD

Drive Weight	<50g
Capacity	128GB
Height	7mm
Length	100.45mm
Width	69.85mm
Interface	SATA 3.0 (6Gb/s)
Performance	Up to Random Read/Write = 70K/40K IOPS
Maximum Sequential Read	Up to 530MB/s
Maximum Sequential Write	Up to 380MB/s
Logical Blocks	250,069,680
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	DIPM; TRIM

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256GB 2.5in SATA Three Layer Cell SSD

Drive Weight	<62g
Capacity	256GB
Height	7mm
Length	100.45mm
Width	69.85mm
Interface	SATA 3.0 (6Gb/s)
Performance	Up to Random Read/Write = 55K/68K IOPS
Maximum Sequential Read	Up to 530MB/s
Maximum Sequential Write	Up to 450MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	DIPM; TRIM
	to define CD 4 billion between TD 4 billion between Astron Germanitation and the large Up to

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.



Technical Specifications - Audio

HIGH DEFINITION AUDIO

Туре	Integrated
HD Stereo Codec	Realtek ALC3601
Audio I/O Ports	Front side Combo jack for supporting CTIA, Rear side Line-in/ Line-out/ Mic-in jacks
Internal Speaker Amplifier	2W class D mono amplifier for the internal speaker only. External speakers must be powered externally.
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speaker.
HD Audio Codec	Realtek ALC3601
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1K/ 48 K/96K / 192K Hz for DAC and 44.1K/ 48K/ 96K/ 192K Hz Hz for ADC
Wavetable Syntheses	Yes
Analog Audio	Yes
# of Channels on Line-Out	Stereo
Internal Speaker	Yes
External Speaker Jack	2W class D mono amplifier for the internal speaker only. External speakers must be powered externally.

Technical Specifications – Power Supply & Weight and Dimensions

POWER SUPPLY

Operating Voltage Range	90 – 264 VAC
Rated Voltage Range	100-240V AC
Rated Line Frequency	50/60 HZ
Operating Line Frequency	47 – 63 Hz
Rated Input Current	180W : <2.3A; 310W: <4A
Rated Input Current with Energy Efficient* Power Supply	180W active PFC 87/90/87% efficient at 20/50/100% load (115V) 88/91/88% efficient at 20/50/100% load (230V); 310W active PFC 87/90/87% efficient at 20/50/100% load (115V) 88/91/88% efficient at 20/50/100% load (230V)
DC Output	+12.1V
Current Leakage (NFPA 99: 2102)	Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.
Power Supply Fan	70*25mm (linear type)

WEIGHT AND DIMENSIONS

Chassis (W x H x D)	6.69 x 13.3 x 10.79 in (170 x 338 x 274 mm)
System Volume	960.06cu in 15.76L
System Weight*	11.9 lbs / 5.4 kg
Max Supported Weight (desktop orientation)	N/A
Tower Stand (H x W x D)	13.42 x 6.69 x 10.92 in (340.8 x 170 x 277.5 mm)
Packaged (H x W x D)	11.46 x 15.35 x 19.65 in 291 x 390 x499 mm
Shipping Weight	17.64lb / 8 kg
Palletization Profile	6 units per layer 7layer max 42 per pallet Footprint -85.31x39.37x47.24 in (2167 x 1000 x1200 mm)



10/100/1000	Ethernet Features	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)	
NIC		100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)	
		1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)	
		Auto-Negotiation (Automatic Speed Selection)	
		Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s	
	Power	ACPI compliant – multiple power modes	
	Management	Situation-sensitive features reduce power consumption	
		Advanced link down power saving for reducing link down power consumption	
	Performance	TCP/IP/UDP Checksum Offload (configurable)	
	Features	Protocol Offload (ARP & NS)	
		Large send offload and Giant send offload	
		Receiving Side Scaling	
		Jumbo Frame 9K	
	Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame);	
		Wake-on-LAN from off (Magic Packet only)	
		PXE 2.1 Remote Boot	
		Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))	
		Comprehensive diagnostic and configuration software suite	
		Virtual Cable Doctor for Ethernet cable status	
	Interface	PCIe + SMBus	
	NIC Device Driver	PCIe GBE Ethernet Family Controller	
	Name		

Γ

Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac		
Interoperability	Wi-Fi certification		
Frequency Bands	802.11b/g/n	• 2.402 – 2.482 GHz	
	802.11a/n	• 4.9 – 4.95 GHz (Japan)	
		• 5.15 – 5.25 GHz	
		• 5.25 – 5.35 GHz	
		• 5.47 – 5.725 GHz	
		• 5.825 – 5.850 GHz	
Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz) 		
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM		
Security ¹	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI 		
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)		
Roaming	IEEE 802.11 compliant roaming between access points		



Queba une Danua	• 802.11b : +14dBm minin	num			
Output Power ²	 802.11g : +12dBm minimum 				
	• 802.11a : +12dBm minin				
	• 802.11n HT20(2.4GHz) :	+12dBm minimum			
	• 802.11n HT40(2.4GHz) :	+12dBm minimum			
	• 802.11n HT20(5GHz) : + 7	IOdBm minimum			
	• 802.11n HT40(5GHz):+*	IOdBm minimum			
	• 802.11ac VHT80(5GHz) :	+10dBm minimum			
Power Consumption	• •Transmit mode2.0 W				
i ower consumption	• Receive mode1.6 W				
	 • Idle mode (PSP)180 mW 	(WLAN Associated)			
	 • Idle mode50 mW(WLAN 	unassociated)			
	 •Connected Standby 10 	mW			
	• Radio disabled8 mW				
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode				
Receiver Sensitivity ³	Receiver Sensitivity ³ • 802.11b, 1Mbps : -93.5dBm maximum				
-	• 802.11b, 11Mbps : -84dBm maximum				
	• 802.11a/g, 6Mbps : -86dBm maximum				
	• 802.11a/g, 54Mbps : -72dBm maximum				
	• 802.11n, MCS07 : -67dBm maximum				
	• 802.11n, MCS15 : -64dBm maximum				
	• 802.11ac, MCS0 : -84dBm maximum				
	• 802.11ac, MCS9 : -59dBn	n maximum			
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth® communications				
Form Factors	PCI-Express M.2 MiniCard				
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm				
Weight	Туре 2230 : 2.8g				
Operating Voltage	3.3v +/- 9%				
Temperature	Operating: Non-operating:	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)			
Humidity	Operating: Non-operating:	10% to 90% (non-condensing) 5% to 95% (non-condensing)			

Altitude	Operating: Non-operating:	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio OFF; LED White – Radio ON		
HP Integrated Module with Bl	uetooth 4.0/4.1/4.2 Wireless	Technology	
Bluetooth [®] Specification	4.0/4.1/4.2 Compliant		
Frequency Band	2402 to 2480 MHz		
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)		
Data Rates and Throughput	Data Rates and Throughput Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps		
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels		
	Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)		
Transmit Power	The Bluetooth [®] component shall operate as a Class II Bluetooth [®] device with a maximum transmit power of + 4 dBm for BR and EDR.		
Receiver Sensitivity Legacy			
Power Consumption	Power Consumption Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW		
Range	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)		
Electrical Interface USB 2.0 compliant			
Bluetooth [®] Software Supported Link Topology	Microsoft Windows Bluetooth® Software		
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark		
Certifications Bluetooth® Profiles Supported	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
Power Management Certifications	Microsoft Windows ACPI, and USB Bus Support		



Г

Certifications	BT4.1-ESR 5/6/7 Compliance
Bluetooth [®] Profiles	LE Link Layer Ping
	LE Dual Mode
Supported	LE Link Layer
	LE Low Duty Cycle Directed Advertising
	LE L2CAP Connection Oriented Channels
	Train Nudging & Interlaced Scan
	BT4.2 ESR08 Compliance
	LE Secure Connection- Basic/Full
	LE Privacy 1.2 –Link Layer Privacy
	LE Privacy 1.2 – Extended Scanner Filter Policies
	LE Data Packet Length Extension
	FAX Profile (FAX)
	Basic Imaging Profile (BIP)2
	Headset Profile (HSP)
	Hands Free Profile (HFP)
	Advanced Audio Distribution Profile (A2DP)
areas. Contact service provider	bonal feature. Connection requires wireless data service contract, network support, and is not available in all to determine the coverage area and availability. Connection speeds will vary due to location, environment, factors. 4G LTE not available on all products or in all countries.
	ts that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with 49 or otherwise disable those channels.
•	release for updates on supported security features.
	red at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g
	ternet service required and not included. Availability of public wireless access points limited.



After-Market Options (availability may vary by region)

Туре	Description	Part #
Memory	HP 4GB DDR4-2666 DIMM	3TK85AA
	HP 8GB DDR4-2666 DIMM	3TK87AA
	HP 16GB DDR4-2666 DIMM	ЗТК8ЗАА
Storage	HP 500GB SATA 6.0Gb/s Hard Drive	QK554AA
	HP 1TB 7200rpm SATA 6Gbps Hard Drive	QK555AA
	HP Turbo Drive Gen2 256GB M.2 SSD Drive	1CA51AA
	Intel Optane Memory 16GB (cache) ****	1WV97AA
	HP 256GB SATA TLC Non-SED Solid State Drive	P1N68AA
	HP 9.5mm G3 8/6/4 SFF G4 400 SFF/MT DVD Writer	1CA53AA
Graphics	NVIDIA® GT 730 2GB DP Card	Z9H51AA
	AMD Radeon™ R7 430 Card	1MX32AA
Security	HP Business PC Security Lock V2 Kit	N3R93AA
	HP Keyed Cable Lock 10mm kit	T1A62AA
Adapters	HP USB to Serial Adapter	J7B60AA
	HP HDMI Standard Cable Kit	T6F94AA
	HP USB to Serial Port Adapter	J7B60AA
Networking	Intel Ethernet I210-T1 GbE NIC Card	E0X95AA
Input	HP USB Mouse	QY777AA
	HP USB Hardened Mouse	P1N77AA
	HP USB Keyboard	QY776AA
	HP PS/2 Business Slim Keyboard	N3R86AA
	HP USB Business Slim Keyboard	N3R87AA
	HP Conferencing Keyboard	K8P74AA
	HP USB Antimicrobial Slim Keyboard and Mouse	Z9H50AA
Others	HP Business Headset v2	
	HP USB Business Speakers v2	N3R89AA

Change Log

© Copyright 2018 HP Development Company, L.P. The information contained herein is subject to change without notice. The only warranties for HP products are set forth in the express limited warranty statements accompanying such products. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein. Microsoft and Windows are registered trademarks or trademarks of Microsoft Corporation in the U.S. and/or other countries. Intel, Celeron[®], Core, Pentium are registered trademarks or trademarks of Intel Corporation in the U.S. and/or other countries. Bluetooth is a trademark of its proprietor, used by HP Inc. under license. NVIDIA, GeForce, Kepler and NVS are trademarks and/or registered trademarks of NVIDIA Corporation in the U.S. and other countries. AMD and Radeon are trademarks of Advanced Micro Devices, Inc. ENERGY STAR is a registered trademark owned by the U.S. Environmental Protection Agency.

Date of change:	Version History:	Change	Description of change:
May 3, 2018	From v1 to v2	Update	Graphics Section
May 14, 2018	From V2 to V3	Added	Environmental Tab
July 5, 2018	From V3 to V4	Added	Call outs added to back and front images and redundant wording removed from pages 1,2,4,6,7,8 and 22.
August 16, 2018	From V4 to V5	Update	Call outs details updated At A Glance disclaimer edited Dicrete Graphics updated Memory section footnote edited Ports updated Bays section moved under ports Environmental and industry table updated Certifications section removed Nvidia GT 730 2GB x8 GC updated 128GB M.2 TLC SSD and 256G M.2 TLC SSD removed 128GB SATA2.5in TLC SSD and 256G SATA 2.5" TLC SSD added
August 21, 2018	From V5 to V6	Update	Dimensions and weight / Weight and dimensions updated
October 17, 2018	From V6 to V7	Update	Audio Line out and Audio Link in switched, pages 2 and 7
November 5, 2018	From V7 to V8	Update	Note added for Security and Protection "Wi-Di" removed from footnote 6
December 12, 2018	From V8 to V9	Update	Memory section footnote added